

## **Product Change Notification / ALAN-230ACF570**

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27-Jul-2023

## **Product Category:**

**OTN Processors & PHYs** 

## **PCN Type:**

Manufacturing Change

# **Notification Subject:**

CCB 6405 Initial Notice: Qualification of SR1 as an additional substrate material for PM6010B1-FEI, PM6011B1-FEI, PM6015B1-FEI, PM6017B1-FEI, and PM6018B1-FEI catalog part numbers (CPN) available in 1932L BBGA (45x45x4.00mm) package.

### **Affected CPNs:**

ALAN-23OACF570\_Affected\_CPN\_07272023.pdf ALAN-23OACF570\_Affected\_CPN\_07272023.csv

### **Notification Text:**

**PCN Status:**Initial Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of SR1 as an additional substrate material for PM6010B1-FEI, PM6011B1-FEI, PM6015B1-FEI, PM6017B1-FEI, and PM6018B1-FEI catalog part numbers (CPN) available in 1932L BBGA (45x45x4.00mm) package.

#### **Pre and Post Change Summary:**

	Pre Change	Post Change			
Assembly Site	Amkor Technology Korea (K4), INC (ATK)	Amkor Technology Korea (K4), INC (ATK)	Amkor Technology Korea (K4), INC (ATK)		
Core Material	E705G	E705G	E705G		
Substrate Material	SR7300GR-B	SR7300GR-B	SR1		
Substrate Material Thickness	21±7.5um	21±7.5um	21±10um		
Process	ABF GZ-41	ABF GZ-41	ABF GL 102		
Bump Material	Sn1.8Ag	Sn1.8Ag	Sn1.8Ag		
Die Attach Material	SCF-5	SCF-5	SCF-5		
Underfill Material	NAU-39	NAU-39	NAU-39		

Impacts to Data Sheet:None

Change ImpactNone

**Reason for Change:**To improve manufacturability by qualifying an additional SR1 substrate material.

**Change Implementation Status:**In Progress

**Estimated Qualification Completion Date:**September 2023

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

## **Time Table Summary:**

	July 2023			>	September 2023						
Workweek	2	2	2	3	3		35	36	37	38	39
	/	8	9	0							
Initial PCN Issue				<sub>v</sub>							
Date											
Qual Report											\ \
Availability											^
Final PCN Issue											
Date											^

Method to Identify Change:Traceability code

**Qualification Plan:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:** July 27, 2023: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

### **Attachments:**

PCN\_ALAN-23OACF570 Qualification Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

PM6010B1-FEI

PM6011B1-FEI

PM6015B1-FEI

PM6017B1-FEI

PM6018B1-FEI

Date: Wednesday, July 26, 2023